

# PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
<b>CONVEYING PARTY DATA</b>													
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Jhy-Ming HUNG</td> <td>06/10/2009</td> </tr> <tr> <td>Jen-Cheng LIU</td> <td>06/10/2009</td> </tr> <tr> <td>Dun-Nian YAUNG</td> <td>06/10/2009</td> </tr> <tr> <td>Chun-Chieh CHUANG</td> <td>06/15/2009</td> </tr> </tbody> </table>		Name	Execution Date	Jhy-Ming HUNG	06/10/2009	Jen-Cheng LIU	06/10/2009	Dun-Nian YAUNG	06/10/2009	Chun-Chieh CHUANG	06/15/2009		
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<b>CORRESPONDENCE DATA</b>													
<p>Fax Number: (214)200-0853  <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 9727398635</p> <p>Email: eppsl@haynesboone.com</p> <p>Correspondent Name: David M. O'Dell</p> <p>Address Line 1: HAYNES AND BOONE, LLP IP Section</p> <p>Address Line 2: 2323 Victory Avenue, Suite 700</p> <p>Address Line 4: Dallas, TEXAS 75219</p>													
ATTORNEY DOCKET NUMBER:	24061.1026												
NAME OF SUBMITTER:	David M. O'Dell												

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**PATENT**  
**REEL: 023191 FRAME: 0207**

Total Attachments: 3

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**ASSIGNMENT**

WHEREAS, we,

- |     |                   |    |  |
|-----|-------------------|----|--|
| (1) | Jyh-Ming Hung     | of | No. 19, Guo Gou 3rd Lane, Guo Gou Village<br>Dacun Township, Changhua County 515, Taiwan, R.O.C. |
| (2) | Jen-Cheng Liu     | of | #219 5F, Guan-Dong Road<br>Hsin Chu City, Taiwan, R.O.C.   |
| (3) | Dun-Nian Yaung    | of | 4F, No. 15, Lane 130, Wansheng Street, Wunshan District<br>Taipei City 116, Taiwan, R.O.C.       |
| (4) | Chun-Chieh Chuang | of | No. 61, Minan Street<br>Tainan City, Taiwan, R.O.C.  |

have invented certain improvements in

**SENSOR STRUCTURE FOR OPTICAL PERFORMANCE ENHANCEMENT**

for which we have executed an application for Letters Patent of the United States of America,

\_\_\_\_\_ of even date filed herewith; and  
  x   filed on June 12, 2009 and assigned application no. 12/483,485 and;

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

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AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Jyh-Ming Hung

Residence Address: No. 19, Guo Gou 3rd Lane, Guo Gou Village  
Dacun Township, Changhua County 515, Taiwan, R.O.C.

Dated: 2009/06/10

Jyh-Ming Hung  
Inventor Signature

Inventor Name: Jen-Cheng Liu

Residence Address: #219 5F, Guan-Dong Road  
Hsin Chu City, Taiwan, R.O.C.

Dated: 2009/06/10

Jen-Cheng Liu  
Inventor Signature

Inventor Name: Dun-Nian Yaung

Residence Address: 4F, No. 15, Lane 130, Wansheng Street, Wunshan District  
Taipei City 116, Taiwan, R.O.C.

Dated: 2009/06/10

Dun-Nian Yaung  
Inventor Signature

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Inventor Name: Chun-Chieh Chuang

Residence Address: No. 61, Minan Street  
Hsin-Chu City, Taiwan, R.O.C.

Dated: 2009/06/15

chun-chieh chuang  
Inventor Signature

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